SURFACE MOUNT SILICON TRIPLE ISOLATED SCHOTTKY DIODE



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMXSH-3 contains three (3) isolated silicon Schottky switching diodes, manufactured by the epitaxial planar process, epoxy molded in an SOT-26 surface mount package, and designed for applications requiring low forward voltage drop

MARKING CODE: XH3



SOT-26 CASE

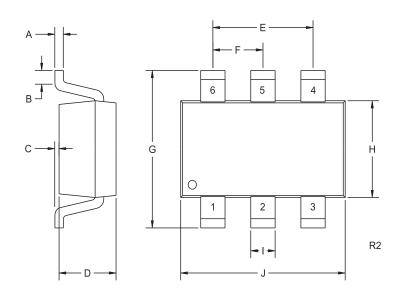
MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Continuous Forward Current	l _F	100	mA
Peak Repetitive Forward Current	I _{FRM}	350	mA
Peak Forward Surge Current, tp=10ms	I _{FSM}	750	mA
Power Dissipation	P_{D}	350	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (T _A =25°C unless otherwise noted)								
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS			
I _R	V _R =25V		90	500	nA			
I_{R}	V _R =25V, T _A =100°C		25	100	μΑ			
BV_R	I _R =100μA	30			V			
٧ _F	I _F =2.0mA		0.29	0.33	V			
V_{F}	I _F =15mA		0.37	0.45	V			
V_{F}	I _F =100mA		0.51	1.00	V			
CJ	V _R =1.0V, f=1.0MHz		7.0		pF			
t _{rr}	$I_F=I_R=10$ mA, $I_{rr}=1.0$ mA, $R_L=100$ Ω			5.0	ns			

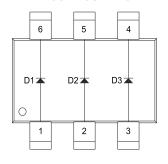
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SOT-26 CASE - MECHANICAL OUTLINE



PIN CONFIGURATION



DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
Α	0.004	0.007	0.11	0.19		
В	0.016	-	0.40	-		
C	-	0.004	-	0.10		
D	0.039	0.047	1.00	1.20		
E	0.074	0.075	1.88	1.92		
F	0.037	0.038	0.93	0.97		
G	0.102	0.118	2.60	3.00		
Ι	0.059	0.067	1.50	1.70		
	0.016		0.41			
J	0.110	0.118	2.80	3.00		

SOT-26 (REV: R2)

LEAD CODE:

- 1) Anode D1
- 2) Anode D2
- 3) Anode D3
- 4) Cathode D3
- 5) Cathode D2
- 6) Cathode D1

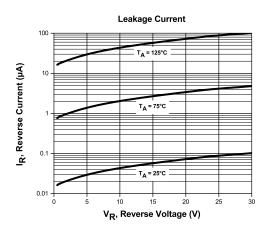
MARKING CODE: XH3

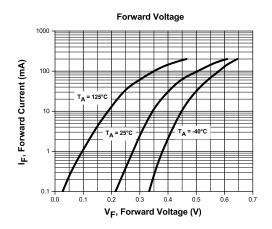
R6 (11-February 2016)

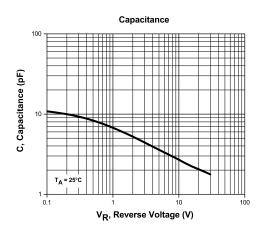
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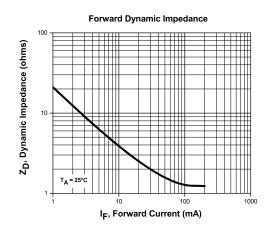


TYPICAL ELECTRICAL CHARACTERISTICS





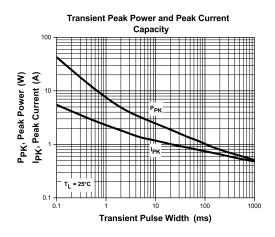


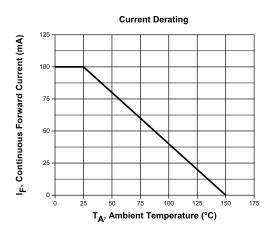


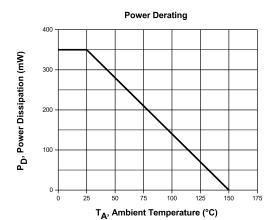




TYPICAL ELECTRICAL CHARACTERISTICS







OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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